ZZ1 These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ2 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ3 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANL: 001

<table>
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<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: PMP10594</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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<tr>
<th>PLOT NAME = Top Assembly Drawing</th>
<th>GENERATED: 12/24/2014 2:24:09 PM</th>
<th>TEXAS INSTRUMENTS</th>
</tr>
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</table>
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